

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV9102SIDGSR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV9102SIDGSR	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGS 10	3x3x1	32.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.033376	96.677577	966776	0.101674	1017
Precious Metals	Gold	7440-57-5	0.000184	0.532978	5330	0.000561	6
Precious Metals	Palladium	7440-05-3	0.000963	2.789445	27894	0.002934	29
Sub-Total			0.034523	100	1000000	0.105168	1052
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.099922	82.000066	820001	0.304394	3044
Thermoplastics	Epoxy	85954-11-6	0.021934	17.999934	179999	0.066818	668
Sub-Total			0.121856	100	1000000	0.371211	3712
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	16.270335	94.649994	946500	49.564525	495645
Magnesium and Its Alloys	Magnesium	7439-95-4	0.030083	0.175003	1750	0.091642	916
Nickel and Its Alloys	Nickel	7440-02-0	0.55008	3.2	32000	1.675716	16757
Other Inorganic Materials	Silicon	7440-21-3	0.124628	0.725003	7250	0.379656	3797
Precious Metals	Silver	7440-22-4	0.214875	1.25	12500	0.654576	6546
Sub-Total			17.190001	100	1000000	52.366115	523661
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.23352	97.3	973000	0.711375	7114
Precious Metals	Gold	7440-57-5	0.00072	0.3	3000	0.002193	22
Precious Metals	Palladium	7440-05-3	0.00504	2.1	21000	0.015353	154
Precious Metals	Silver	7440-22-4	0.00072	0.3	3000	0.002193	22
Sub-Total			0.24	100	1000000	0.731115	7311
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	13.932715	93.500003	935000	42.443404	424434
Other Plastics and Rubber	Carbon Black	1333-86-4	0.074506	0.499997	5000	0.226969	2270
Thermoplastics	Epoxy	85954-11-6	0.894078	6	60000	2.723641	27236
Sub-Total			14.901299	100	1000000	45.394014	453940
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.338894	100	1000000	1.032377	10324
Sub-Total			0.338894	100	1000000	1.032377	10324
Total			32.826573			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.